

1 **In the Specification:**

2  
3 Please replace the paragraph at lines 10—21 on page 4 with the following:

4  
5 One exemplary embodiment of the laser machining process will be  
6 described in the context of forming slots in a substrate. Such slots can be used for,  
7 among other things, fluid feed slots. In one exemplary embodiment, a substrate  
8 containing fluid feed slots can be incorporated into a print head or other fluid  
9 ejecting device. As commonly used in ~~print-head-die~~print head device, the  
10 substrate can comprise a semiconductor substrate that has microelectronics  
11 incorporated within and supported by the substrate. In one exemplary  
12 embodiment, the fluid feed slot(s) allow a fluid such as ink to be supplied to fluid  
13 ejecting elements contained in ejection chambers within the print head. The fluid  
14 ejection elements commonly comprise firing resistors that heat ink causing  
15 increased pressure in the ejection chamber. A portion of that ink can be ejected  
16 through a firing nozzle with the ink being replaced by ink from the ink feed slot.  
17  
18  
19  
20  
21  
22  
23  
24  
25